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\*\* CONTINUING DATA \*\*\*\*\* *YK*

This application is a DIV of 09/797,206 02/27/2001 PAT 6,693,039

\*\* FOREIGN APPLICATIONS \*\*\*\*\* *YK*

EUROPEAN PATENT OFFICE (EPO) 00830148.3 02/29/2000

## IF REQUIRED, FOREIGN FILING LICENSE GRANTED

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Foreign Priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no	STATE OR	SHEETS	TOTAL	INDEPENDENT
35 USC 119 (a-d) conditions met <input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance	COUNTRY	DRAWING	CLAIMS	CLAIMS
Verified and Acknowledged <i>gzhuh</i> Examiner's Signature	ITALY	3	17	3
Initials				

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## TITLE

Process for forming a buried cavity in a semiconductor material wafer and a buried cavity

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